

IN THE CLAIMS

BEST AVAILABLE COPY

Please cancel ~~Claims 13-20~~.

Please add the following **Claims 21-28**.

21. A method for securing a printed circuit board to a rigidizer comprising steps of:
applying a liquid adhesive to a top surface of the rigidizer;
curing the liquid adhesive during a first curing stage, after application of the liquid adhesive,
to produce a partially cured liquid adhesive;
placing the printed circuit board on the partially cured liquid adhesive; and
curing the partially cured liquid adhesive during a second curing stage to produce a fully
cured liquid adhesive.
22. The method of claim 21, wherein the step of applying the liquid adhesive to the top surface of
the rigidizer comprises a step of screening the liquid adhesive onto the top surface of the rigidizer.
23. The method of claim 21, wherein the liquid adhesive is a dual-cure system adhesive.
24. The method of claim 21, wherein the step of curing of the liquid adhesive during a first stage
produces a tacky adhesive that spreads, at most, a negligible amount when the printed circuit board is
placed on the partially-cured liquid adhesive.
25. The method of claim 21, further comprising a step of bending the printed circuit board and
the rigidizer after the second cure of the liquid adhesive.
26. The method of claim 21, wherein the liquid adhesive is a heat-curable liquid adhesive,
wherein the first cure comprises applying a first heating stage to the liquid adhesive and wherein the
second cure comprises applying a second heating stage to the liquid adhesive.
27. The method of claim 21, wherein the liquid adhesive can be cured by exposure to ultraviolet
radiation.

28. The method of claim 21, wherein the liquid adhesive can be cured by any one of a plurality of curing methods, wherein the first cure comprises applying a first curing method of the plurality of curing methods to the liquid adhesive and wherein the second cure comprises applying a second, different curing method of the plurality of curing methods to the liquid adhesive.

Attached hereto as ATTACHMENT A is a mark-up version of the changes made to the specification and claims by the current amendment and response. The attached pages are captioned "**Version with Markings to Show Changes Made.**"

BEST AVAILABLE COPY